

Status: EU Directives are being published on this site to aid cross referencing from UK legislation. After IP completion day (31 December 2020 11pm) no further amendments will be applied to this version.

ANNEX

In Annex III, entry 15 is replaced by the following:

15	Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit flip chip packages	Applies to categories 8, 9 and 11 and expires on: — 21 July 2021 for categories 8 and 9 other than in vitro diagnostic medical devices and industrial monitoring and control instruments; — 21 July 2023 for category 8 in vitro diagnostic medical devices; — 21 July 2024 for category 9 industrial monitoring and control instruments, and for category 11.
15(a)	Lead in solders to complete a viable electrical connection between the semiconductor die and carrier within integrated circuit flip chip packages where at least one of the following criteria applies: — a semiconductor technology node of 90 nm or larger; — a single die of 300 mm ² or larger in any semiconductor technology node; — stacked die packages with die of 300 mm ² or larger, or silicon interposers of 300 mm ² or larger.	Applies to categories 1 to 7 and 10 and expires on 21 July 2021.